

SIGNAL PROCESSING TECHNOLOGIES

SPT231

FAST SETTLING, WIDEBAND BUFFER/AMPLIFIER (A_V = \pm 1 to \pm 5)

General Description

The SPT231 Buffer/Amplifier is a wideband operational amplifier designed specifically for high-speed, low-gain applications. The SPT231 is based on a current feedback op amp topology-a unique design that both eliminates the gain-bandwidth tradeoff and permits unprecedented high-speed performance. (See table below.)

The SPT231 Buffer/Amplifier is the ideal design alternative to low precision open-loop buffers and oscillation-prone conventional op amps. The SPT231 offers precise gains from ± 1.000 to ± 5.000 and linearity that is a true 0.1%-even for demanding 50Ω loads. Open-loop buffers, on the other hand, offer a nominal gain of 0.95 ± 0.03 and a linearity of only 3% for typical loads. A buffer's settling time may look impressive but it is usually specified at unrealistically large load resistances or when the effects of thermal tail are not included; the SPT231 Buffer/Amplifier settles to 0.05% in 15ns-while driving a 100Ω load.

Offsets and drifts, usually a low priority in conventional high-speed op amp designs, were not ignored in the SPT231; the input offset voltage is typically 1mV and input offset voltage drift is only $10\mu\text{V}/^{\circ}\text{C}$. The SPT231 is stable and oscillation-free across the entire gain range and since it's internally compensated, the user is saved the trouble of designing external compensation networks and having to "tweak" them in production. The absence of a gain-bandwidth tradeoff in the SPT231 allows performance to be predicted easily; the table below shows how the bandwidth is affected very little by changing the gain setting.

The SPT231 is constructed using thin film resistor/bipolar transistor technology, and is available in the following versions:

SPT231AIH -25°C to +85°C 12-pin TO-8 can

SPT231AMH -55°C to +125°C 12-pin TO-8 can, features burn-

in and hermetic testing

Typical Performance

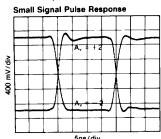
	gain setting						
parameter	1	2	5	1	-2	-5	units
-3dB bandwidth	180	165	130	165	150	115	MHz
rise time (2V)	1.8	2.0	2.5	2.0	2.2	2.9	ns
slew rate	2.5	3	3	3	3	3	V/ns
settling time (to .1%)	12	12	12	12	12	15	ns

Features

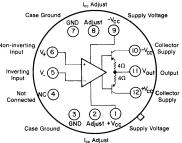
- 165MHz closed-loop -3dB bandwidth
- 15ns settling to 0.05%
- 1mV input offset voltage, 10µV/°C drift
- 100mA output current
- Excellent AC and DC linearity
- Direct replacement for CLC231

Applications

- Driving flash A/D converters
- Precision line driving (a gain of 2 cancels matched-line losses)
- DAC current-to-voltage conversion
- Low-power, high-speed applications (50mW @ ±5V)

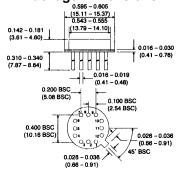


Bottom View



Pins 2 and 8 are used to adjust the supply current or to adjust the offset voltage (see text). These pins are normally left

Package Dimensions



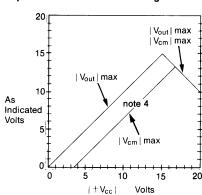
Signal Processing Technologies, Inc.

SPT231 Electrical Characteristics ($A_v = +2$, $V_{cc} = \pm 15V$, $R_L = 100\Omega$, $R_f = 250\Omega$; unless specified) CONDITIONS MAX & MIN RATINGS UNITS **PARAMETERS** TYP SYMBOL Ambient Temperature SPT231AIH +25°C -55°C +25°C +125°C SPT231AMH +25°C -25°C +25°C +85°C **Ambient Temperature** FREQUENCY DOMAIN PERFORMANCE >145 >120 **SSBW** t-3dB bandwidth note 2 MHz $V_{out} \leq 2V_{pp}$ 165 >145 $V_{out} \le 10 V_{pp}$ 95 >80 >80 >60 MHz **FPBW** $V_{out} \leq 2V_{pp}$ gain flatness note 2 0.1 to 50MHz < 0.6 < 0.3 < 0.6 dB **GFPL** peaking 0.1 peaking >50MHz <1.5 < 0.3 < 0.8 dB **GFPH** 0.1 rolloff at 100MHz < 0.6 < 0.6 dB **GFR** 0.4 <1.0 group delay to 100MHz 3.5 ± 0.5 GD ns <2 <2 linear phase deviation to 100MHz 0.5 <2 **LPD** reverse isolation to 100MHz non-inverting 53 >43 >43 >43 dB RINI inverting 36 >26 >26 >26 dB RIIN TIME DOMAIN PERFORMANCE rise and fall time 2V step <2.4 <2.3 <2.7 **TRS** ns 10V step 5.0 **TRL** <7.0 < 6.5 < 6.5 ns settling time to .05% 5V step 15 ns TS 2.5V step **TSP** 12 <22 <17 <22 to .1% ns overshoot 5V step 5 <15 <10 <15 os 3 >2.5 V/ns slew rate (overdriven input) >2.5 >1.8SR overload recovery <1% error <50ns pulse, 200% overdrive 120 OR ns DISTORTION AND NOISE PERFORMANCE dBc + 2nd harmonic distortion 0dBm, 20MHz -55<-47 <-47 <-47 HD2 + 3rd harmonic distortion 0dBm, 20MHz -59<-47 < -47<-47 dBc HD3 equivalent input noise noise floor SNF >5MHz -153 <-150 <-150 dBm(1Hz) < -150integrated noise 5MHz to 200MHz 70 <100 <100 <100 _μVrms INV STATIC, DC PERFORMANCE input offset voltage <4.0 <2.0 <4.5 m۷ VIO μV/°C temperature coefficient <25 <25 <25 DVIO 10 * input bias current non-inverting 5 <29 <21 <31 μΑ **IBN** temperature coefficient 50 <125 <125 nA/°C DIBN <125 * input bias current inverting 10 <31 <15 <35 IBI μΑ temperature coefficient 125 <200 <200 <200 nA/°C DIBI * power supply rejection ratio 50 **PSRR** >45 >45 >45 dB common mode rejection ratio 46 >40 >40 >40 dB **CMRR** * supply current 18 <22 <22 <22 ICC no load mΑ MISCELLANEOUS PERFORMANCE non-inverting input resistance 400 >100 >200 >400 $k\Omega$ RIN CIN capacitance 1.3 <2.5 <2.5 <2.5 pF output impedance at 100MHz 5,37 ZO Ω ,nH output voltage range >±11 $>\pm 11$ no load +12 $>\pm 11$

Min/max ratings are based on product characterization and simulation. Individual parameters are tested as noted. Outgoing quality levels are determined from tested parameters.

Absolute Maximum Ratings

Input and Common Mode Voltage Limits



lead temperature (soldering 10s) $+300^{\circ}$ C

note 1:* AIH, AMH 100% tested at 25°C.

† AMH 100% tested at +25°C & sample tested at-55°C & +125°C.

† AIH sample tested at +25°C.

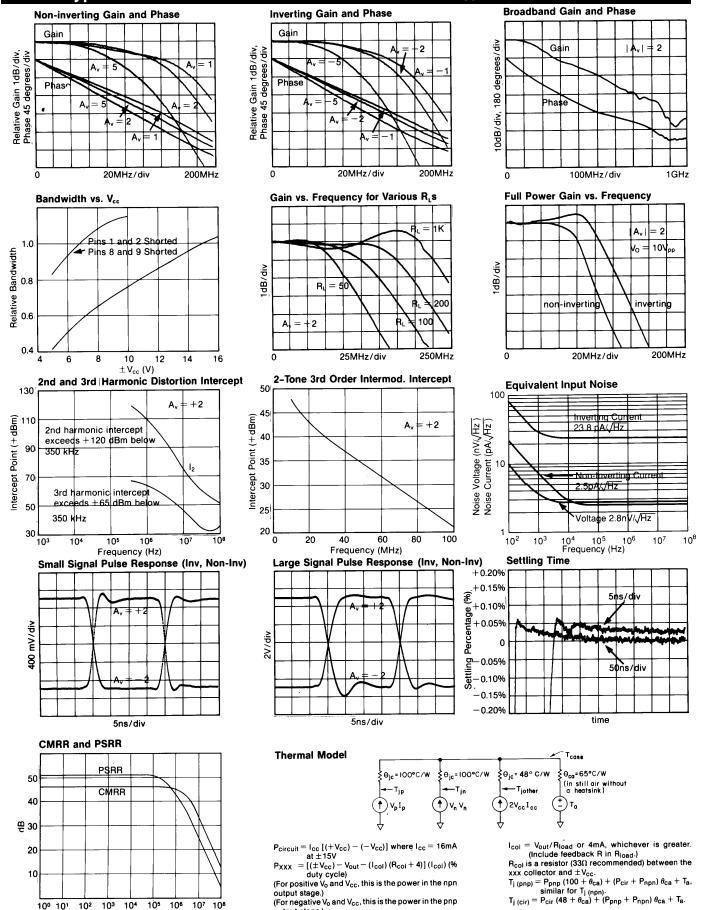
 $\textbf{note 2:} \ The \ output \ amplitude \ used \ in \ testing \ is \ 0.63 V_{pp}. \ Performance \ is \ guaranteed \ for \ conditions \ listed.$

note 3: In the non-inverting configuration, care should be taken when choosing $R_{\rm i}$, the input impedance setting resistor; bias currents of typically $5\mu{\rm A}$ but as high as $24\mu{\rm A}$ can create an input signal large enough to cause overload. It is therefore recommended that $R_{\rm i} < (V_{cc}/A_v)/24\mu{\rm A}$.

note 4: These ratings protect against damage to the input stage caused by saturation of either the input or output stages at lower supply voltages, and against exceeding transistor collector-emitter breakdown ratings at high supply voltages. V_{out}(max) is calculated by assuming no output saturation. Saturation is allowed to occur up to this calculated level of V_{out}. V_{cm} is defined as the voltage at the non-inverting input, pin 6.



SPT231 Typical Performance Characteristics (T_A = 25°, A_V = +2, V_{CC} = ±15V, R_L = 100Ω; unless specified)



Frequency (Hz)

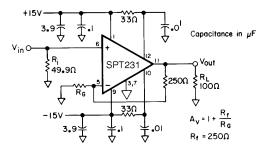


Figure 1: suggested non-inverting gain circuit

Operation

The SPT231 Buffer/Amplifier is based on the current feedback op amp topology, a design that uses current feedback instead of the usual voltage feedback.

The use of the SPT231 is basically the same as that of the conventional op amp (see the gain equations above). Since the device is designed specifically for low gain applications, the best performance is obtained when the circuit is used at gains between ± 1 and ± 5 . Additionally, performance is optimum when a 250Ω feedback resistor is used.

Layout Considerations

To assure optimum performance the user should follow good layout practices which minimize the unwanted coupling of signals between nodes. During initial breadboarding of the circuit, use direct point to point wiring, keeping the lead lengths to less than .25". The use of solid, unbroken ground plane is helpful. Avoid wire-wrap type pc boards and methods. Sockets with small, short pin receptacles may be used with minimal performance degradation although their use is not recommended.

During pc board layout, keep all traces short and direct. The resistive body of Ra should be as close as possible to pin 5 to minimize capacitance at that point. For the same reason, remove ground plane from the vicinity of pins 5 and 6. In other areas, use as much ground plane as possible on one side of the board. It is especially important to provide a ground return path for current from the load resistor to the power supply bypass capacitors. Ceramic capacitors of .01 to $.1\mu$ F (with short leads) should be less than .15 inches from pins 1 and 9. Larger tantalum capacitors should be placed within one inch of these pins. Vcc connections to pins 10 and 12 can be made directly from pins 9 and 1, but better supply rejection and settling time are obtained if they are separately bypassed as in figures 1 and 2. To prevent signal distortion caused by reflections from impedance mismatches, use terminated microstrip or coaxial cable when the signal must traverse more than a few inches.

Since the pc board forms such an important part of the circuit, much time can be saved if prototype boards of any high frequency sections are built and tested early in the design phase. Evaluation boards designed for either inverting or non-inverting gains are available.

Thermal Considerations

At high ambient temperatures or large internal power dissipations, heat sinking is required to maintain acceptable junction temperatures. Use the thermal model on the previous page to determine junction temperatures. Many styles of heat sinks are available for TO-8 packages; the Thermalloy 2240 and 2268 are

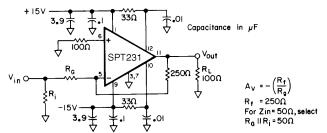


Figure 2: suggested inverting gain circuit

good examples. Some heat sinks are the radial fin type which cover the pc board and may interfere with external components. An excellent solution to this problem is to use surface mounted resistors and capacitors. They have a very low profile and actually improve high frequency performance. For use of these heat sinks with conventional components, a .1" high spacer can be inserted under the TO-8 package to allow sufficient clearance.

Low Vcc Operation: Supply Current Adjustment

The SPT231 is designed to operate on supplies as low as \pm 5V. In order to improve full bandwidth at reduced supply voltages, the supply current (I_{cc}) must be increased. The plot of Bandwidth vs V_{cc} shows the effect of shorting pins 1 and 2 and pins 8 and 9; this will increase both bandwidth and supply current. Care should be taken to not exceed the maximum junction temperatures; for this reason this technique should not be used with supplies exceeding \pm 10V. For intermediate values of V_{cc}, external resistors between pins 1 and 2 and pins 8 and 9 can be used.

Offset Voltage Adjustment

If trimming of the input offset voltage ($V_{os} = V_{ni} - V_{in}$) is desired, a resistor value of $10 k\Omega$ to $1M\Omega$ placed between pins 8 and 9 will cause V_{os} to become more negative by 8mV to 0.2mV respectively. Similarly, a resistor placed between pins 1 and 2 will cause V_{os} to become more positive.

Distortion and Noise

The graphs of intercept point, I_2 and I_3 , versus frequency on the preceding page make it easy to predict the distortion at any frequency given the output voltage of the SPT231. First, convert the output voltage (V₀) to $V_{RMS} = (V_{PP}/2\sqrt{2})$ and then to $P = [(10\log_{10}(20V_{RMS}^2)]$ to get the power output in dBm. At the frequency of interest, its 2nd harmonic will be $S_2 = (I_2 - P) dB$ below the level of P. Its third harmonic will be P0 below P1, as will the two-tone third order intermodulation products. These approximations are useful for P1 dB compression levels.

Approximate noise figure can be determined for the SPT231 using the equivalent input noise graph on the preceding page. The following equation can be used to determine noise figure (F) in dB.

$$F = 10log \left[1 + \frac{v_n^2 + \frac{i_n^2 R_F^2}{A_v^2}}{4kTR_s \Delta f} \right]$$

Where v_n is the rms noise voltage and i_n is the rms noise current. Beyond the breakpoint of the curves (i.e., where they are flat), broadband noise figure equals spot noise figure, so Δf should equal one (1) and v_n and i_n should be read directly off the graph. Below the breakpoint, the noise must be integrated and Δf set to the appropriate bandwidth.

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